



April 16, 2004

To: Harvey Waltersdorf (Chairman EIA CE 2.0)
William Peverill (Secretary EIA CE2.0)

From: Jeff Toran (Technical Advisor – IEC TC48)

C: Carl Fritz (Assistant Secretary IEC SC48B)

RE: IEC Connector Standards Meetings – report for EIA CE2.0

The IEC TC48 Connector & Mechanical Enclosure Standards meetings were held November 2003. The items (briefly) captured below relate to the Connector sub-committee activity and some general areas. There are additional connector standards under development and several in the Mechanical Enclosure's group. If you would like more information please contact me.

Countries participating:

France, Germany, Italy, Japan, Netherlands, United Kingdom and USA.

Projects under preparation:

1. USB + Power (both style A and B as separate standards). Anticipated publication, 4Q04.
2. The Japanese National Committee introduced the 4 position IEEE 1394 connector for standardization. This is done at the request of IEC TC100 TA4, Audio, Video, Multimedia Systems and Equipment – Digital Systems interfaces. Anticipated publication 3Q05.
3. Infiniband I/O cable connector. Anticipated publication 4Q05.
4. RJ45 Industrial Ethernet standard. In draft form; not sure of publication date.
5. Category 5 & 6 Connector standards. Separate standards are being prepared. Anticipated publication 4Q04 for the Cat 5 standard and 4Q05 for the Cat 6.
6. Revised Connector test schedules. Anticipated publication 2Q05.
7. Eye pattern and jitter test method, (60512-25-6 when published). Anticipated publication 4Q04.
8. VSWR, Impedance, reflection coefficient test method, (60512-25-7 when published). Anticipated publication 4Q04.

Attachment No. 3

9. Numerous (over 30) of published 60512 series test methods are being revised/modernized. Publication will occur between 2Q01 through 4Q05.

Other items of note

1. A sister IEC committee (TC91) is drafting a 'resistance to soldering heat test method, (for 'lead-free' products) for surface mount devices. Will be published as IEC 60068-2-058, Environmental testing - Part: 2-58: Tests - Test Td - Test methods for solderability resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD). Anticipated publication is 3-4Q04.
2. A task group has been formed an informal to develop/identify a connector for IEC standardization suitable for Category 8 performance and above for telecommunications usage.

Upcoming Meetings

- 1) May 10-12, 2004 - Hosted by Japan.
- 2) Fall 2004 – Dates & location not finalized.